



Material Content Data Sheet



Sales Product Name				IKFW60N60EH3		Issued		3. July 2019	
MA#				MA001674418					
Package				PG-HSIP247-3-1		Weight*		5919.38 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	2.181	0.04	0.04	368	368	
chip_2	inorganic material	silicon	7440-21-3	5.465	0.09	0.09	923	923	
leadframe	inorganic material	phosphorus	7723-14-0	0.164	0.00		28		
	non noble metal	iron	7439-89-6	0.545	0.01		92		
	non noble metal	copper	7440-50-8	544.561	9.20	9.21	91996	92116	
wire	non noble metal	aluminium	7429-90-5	15.558	0.26	0.26	2628	2628	
encapsulation	inorganic material	zincoxide	1314-13-2	6.001	0.10		1014		
	plastics	silicone resin	-	13.501	0.23		2281		
	organic material	carbon black	1333-86-4	21.685	0.37		3663		
	inorganic material	alumina	1344-28-1	130.514	2.20		22049		
	plastics	epoxy resin	-	412.024	6.96		69606		
	inorganic material	silicondioxide	60676-86-0	1734.836	29.31	39.17	293077	391690	
leadfinish	non noble metal	tin	7440-31-5	16.291	0.28	0.28	2752	2752	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.456	0.01	0.01	77	78	
solder	non noble metal	antimony	7440-36-0	0.553	0.01		93		
	noble metal	silver	7440-22-4	1.383	0.02		234		
	non noble metal	tin	7440-31-5	3.597	0.06	0.09	608	935	
heatspreader	inorganic material	phosphorus	7723-14-0	0.903	0.02		153		
	non noble metal	iron	7439-89-6	3.010	0.05		509		
	non noble metal	copper	7440-50-8	3006.154	50.78	50.85	507848	508510	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com